


△1 Substrate: 0.0625"±0.007" FR4/G10 or equivalent high temp material. 1/2 oz. Cu clad. SnPb plating

△2 Pins: Material- Brass Alloy 360 1/2 hard; finish- 10μ" Au over 50μ" Ni (min.).

△3 Pins: shell material- Brass Alloy 360 1/2 hard; finish- 10μ" Au over 50μ" Ni (min.). Contact material- BeCu; finish 10μ" Au over 100μ" Ni (min.)

All tolerances: ±0.005" (unless stated otherwise). Materials and specifications are subject to change without notice.

<b>PC-DIP/DIP32-02 Drawing</b>		Status: Released	Scale: 2:1	Rev: D
	© 1997 IRONWOOD ELECTRONICS, INC. PO BOX 21151 ST. PAUL, MN 55121 Tele: (651) 452-8100		Drawing: P. Jasmin      Date: 12/17/90	
				File: PC-DIP/DIP32-02 Dwg, MC